TE0712 Test Board

Revision v.48

Exported on 2024-07-29

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4 Overview

Refer to http://trenz.org/te0712-info for the current online version of this manual and other available documentation.

For directly getting started with the prebuilt files jump to the section Launch .

4.1 Key Features

- Vitis/Vivado 2022.2
- PetaLinux
- MicroBlaze
- SPI ELF Bootloader
- I2C
- Flash
- MIG
- FMeter
- SI5338 initialisation with MCS (REV02)
- ETH
- EEPROM MAC

4.2 Revision History

Date	Vivado	Project Built	Authors	Description
2023-05-08	2022.2	TE0712-test_board_noprebuilt-vivado_2022.2-build_0_20230508174410.zip TE0712-test_board-vivado_2022.2-build_0_20230508174410.zip	Waldemar Hanemann	• 2022.2 update • added Si5338 initialisation option in SC0712
2022-08-15	2021.2	TE0712-test_board_noprebuilt-vivado_2021.2-build_15_20220815080800.zip TE0712-test_board-vivado_2021.2-build_15_20220815080800.zip	Waldemar Hanemann	• reduced bitdelay in PLL I2C programming for faster startup • update TE Board Part List
2022-02-16	2021.2	TE0712-test_board_noprebuilt-vivado_2021.2-build_11_20220216064240.zip TE0712-test_board-vivado_2021.2-build_11_20220216064240.zip	Waldemar Hanemann	• new spi bootloader by Henrik Brix Andersen • adjusted offsets

Date	Vivado	Project Built	Authors	Description
2022-01-18	2021.2	TE0712-test_board_noprebuilt-vivado_2021.2-build_8_20220118131243.zip TE0712-test_board-vivado_2021.2-build_8_20220118131243.zip	Waldemar Haneman n	• MB_MCS elf-File bugfix • eeprom Skript bugfix
2022-01-11	2021.2	TE0712-test_board_noprebuilt-vivado_2021.2-build_7_20220111091553.zip TE0712-test_board-vivado_2021.2-build_7_20220111091553.zip	Waldemar Haneman n	• 2021.2 update • added eeprom interface for MAC address read-out • added boot script
2021-06-28	2020.2	TE0712-test_board_noprebuilt-vivado_2020.2-build_5_20210628072407.zip TE0712-test_board-vivado_2020.2-build_5_20210628072421.zip	Manuela Strücker	• 2020.2 update • document style update • update TE Board Part List
2020-03-25	2019.2	TE0712-test_board_noprebuilt-vivado_2019.2-build_8_20200325074937.zip TE0712-test_board-vivado_2019.2-build_8_20200325074915.zip	John Hartfiel	• Script update
2020-01-22	2019.2	TE0712-test_board_noprebuilt-vivado_2019.2-build_3_20200122155446.zip TE0712-test_board-vivado_2019.2-build_3_20200122152018052855355.zip	John Hartfiel	• update for linux user • new script features
2020-01-08	2019.2	TE0712-test_board_noprebuilt-vivado_2019.2-build_2_20200108161124.zip TE0712-test_board-vivado_2019.2-build_2_20200108155510.zip	John Hartfiel	• 2019.2 update • Vitis support

Date	Vivado	Project Built	Authors	Description
2019-04-18	2018.3	TE0712-test_board_noprebuilt-vivado_2018.3-build_05_20190418082456.zip TE0712-test_board-vivado_2018.3-build_05_20190418082240.zip	John Hartfiel	• MCU depends on EOS now
2019-02-22	2018.3	TE0712-test_board_noprebuilt-vivado_2018.3-build_01_20190222073819.zip TE0712-test_board-vivado_2018.3-build_01_20190222073754.zip	John Hartfiel	• TE Script update • linux changes • SCU rework • SI5338 CLKBuilder Pro Project
2018-09-05	2018.2	te0712-test_board-vivado_2018.2-build_03_20180906071356.zip te0712-test_board_noprebuilt-vivado_2018.2-build_03_20180906071434.zip	John Hartfiel	• change block design: qspi clks, clock wizard(REV01 only) • change timing constrains • add hello_te0712 application • new SREC bootloader version • change linux device tree
2018-05-25	2017.4	te0712-test_board-vivado_2017.4-build_10_20180525155402.zip te0712-test_board_noprebuilt-vivado_2017.4-build_10_20180525155555.zip	John Hartfiel	• solved eth issue for REV01 • changed design + second design for REV01
2018-04-12	2017.4	te0712-test_board-vivado_2017.4-build_07_20180412081225.zip te0712-test_board_noprebuilt-vivado_2017.4-build_07_20180412081253.zip	John Hartfiel	• bugfix constrain file - ETH REFCLK, timing

Date	Vivado	Project Built	Authors	Description
2018-03-28	2017.4	te0712-test_board-vivado_2017.4-build_07_20180328145151.zip te0712-test_board_noprebuilt-vivado_2017.4-build_07_20180328145135.zip	John Hartfiel	• new assembly variant
2018-01-08	2017.4	te0712-test_board-vivado_2017.4-build_02_20180108155712.zip te0712-test_board_noprebuilt-vivado_2017.4-build_02_20180108155735.zip	John Hartfiel	• no design changes • small constraint changes
2017-12-15	2017.2	te0712-test_board-vivado_2017.2-build_07_20171215172447.zip te0712-test_board_noprebuilt-vivado_2017.2-build_07_20171215172514.zip	John Hartfiel	• add SI5338 initialisation with MCS • add Ethernet IP
2017-11-07	2017.2	te0712-test_board-vivado_2017.2-build_05_20171107172917.zip te0712-test_board_noprebuilt-vivado_2017.2-build_05_20171107172939.zip	John Hartfiel	• add wiki link in Boart Part Files • set correct short link for te0712-02-200-2c
2017-10-05	2017.2	te0712-test_board-vivado_2017.2-build_03_20171005082148.zip te0712-test_board_noprebuilt-vivado_2017.2-build_03_20171005082225.zip	John Hartfiel	• initial release

Table 1: Design Revision History

4.3 Release Notes and Known Issues

Issues	Description	Workaround	To be fixed version
scu_te0712.elf is not automatically built with TE::sw_run_vitis -all	Domain name can't be found while trying to build scu_te0712.elf	Spelling mistake in apps_list.csv, replace all "msc" with "mcs"	**solved** with 20220815 update
For PCB REV01 only: prebuilt does not boot	There is a Pullup missing on REV01 I2C SCL, so SI5338 configuration over MCS fails	Remove MCS	**solved** with 20180528 update
For PCB REV01 only: CLK1B is not available on	additional clk is not connected on PCB	use other internal generated CLK, maybe more effort is needed to get ETH running	**solved** with 20180528 update

Table 2: Known Issues

4.4 Requirements

4.4.1 Software

Software	Version	Note
Vitis	2022.2	needed, Vivado is included into Vitis installation
PetaLinux	2022.2	needed
SI ClockBuilder Pro	---	optional

Table 3: Software

4.4.2 Hardware

TE Board Part Files.[1]
Complete List is available on "<project folder>\board_files*_board_files.csv"

Design supports following modules:

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	EMMC	Others	Notes
REVISION 01 Modules are no longer supported with reference design 2022.2 and higher	--	REV01 NOT SUPPORTED	--	--	--	--	--
TE0712-02-100-1I	02_100_1i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-100-2C	02_100_2c_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-100-2C3	02_100_2c_1gb	REV02	1 GB	32MB	NA	2.5 mm Samtec connectors	NA
TE0712-02-100-2CA	02_100_2ca_1gb	REV02	1 GB	32MB	NA	NA	Micron QSPI Flash
TE0712-02-200-1I	02_200_1i_1gb	REV02	1 GB	32MB	NA	NA	NA

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[1] https://wiki.trenz-electronic.de/display/PD/TE+Board+Part+Files

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	EMMC	Others	Notes
TE0712-02-200-1I3	02_200_1i_1gb	REV02	1 GB	32MB	NA	2.5 mm Samtec connectors	NA
TE0712-02-200-2C	02_200_2c_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-200-2C3	02_200_2c_1gb	REV02	1 GB	32MB	NA	2.5 mm Samtec connectors	NA
TE0712-02-200-2I	02_200_2i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-35-2I*	02_35_2i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-42I36-A	02_35_2i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-71I06-M	02_100_1i_1gb	REV02	0 GB	32MB	NA	NA	Without DDR
TE0712-02-71I36-A	02_100_1i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-72C03-M	02_100_2ca_1gb	REV02	0 GB	32MB	NA	NA	Without DDR

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	EMMC	Others	Notes
TE0712-02-72C06-M	02_100_2c_1gb	REV02	0 GB	32MB	NA	NA	Without DDR
TE0712-02-72C36-A	02_100_2c_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-72C36-C	02_100_2c_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-72C36-L	02_100_2c_1gb	REV02	1 GB	32MB	NA	2.5 mm Samtec connectors	NA
TE0712-02-81I36-A	02_200_1i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-81I36-AC	02_200_1i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-81I36-L	02_200_1i_1gb	REV02	1 GB	32MB	NA	2.5 mm Samtec connectors	NA
TE0712-02-81I36-X	02_200_1i_1gb	REV02	1 GB	32MB	NA	2.5 mm Samtec connectors	NA
TE0712-02-82C11-P	02_200_2c_1gb	REV02	1 GB	32MB	NA	NA	NA

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	EMMC	Others	Notes
TE0712-02-82C36-A	02_200_2c_1gb	REV02	1GB	32MB	NA	NA	NA
TE0712-02-82C36-AW	02_200_2c_1gb	REV02	1GB	32MB	NA	NA	NA
TE0712-02-82C36-L	02_200_2c_1gb	REV02	1GB	32MB	NA	2.5 mm Samtec connectors	NA
TE0712-02-82C36-P	02_200_2c_1gb	REV02	1GB	32MB	NA	NA	NA
TE0712-02-82I36-A	02_200_2i_1gb	REV02	1GB	32MB	NA	NA	NA
TE0712-02-100-2C2	02_100_2c2_1gb	REV02	1GB	32MB	NA	NA	Special SI5338 Config
TE0712-02-S001	02_200_2c_1gb	REV02	1GB	32MB	NA	2.5 mm Samtec connectors	NA
TE0712-02-S002	02_200_2i_1gb	REV02	1GB	32MB	NA	NA	NA
TE0712-02-S003	02_200_2i_1gb	REV02	1GB	32MB	NA	NA	NA

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	EM MC	Others	Notes
TE0712-02-S005	02_200_2i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-S006	02_100_1i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-S007	02_100_1i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-S008	02_200_2i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-S009	02_100_1i_1gb	REV02	1 GB	32MB	NA	NA	NA
TE0712-02-S004	02_200_1ix_1gb	REV02	1 GB	256MB	NA	NA	Macronix QSPI Flash
TE0712-02-71I01-M	02_100_1i_1gb	REV02	0 GB	32MB	NA	NA	Without DDR
TE0712-03-42I36-A	35_2i_1gb	REV03	1 GB	32MB	NA	NA	NA
TE0712-03-71I36-A	100_1i_1gb	REV03	1 GB	32MB	NA	NA	NA

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	EMMC	Others	Notes
TE0712-03-72C36-A	100_2c_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-72C36-L	100_2c_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-81I36-A	200_1i_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-81I36-L	200_1i_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-82C36-A	200_2c_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-82C36-AW	200_2c_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-82C36-L	200_2c_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-82I36-A	200_2i_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-S004	200_2c_1gb	REV03	1GB	32MB	NA	NA	NA

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	EMMC	Others	Notes
TE0712-03-S006	200_2c_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-S008	200_2i_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-S009	200_2i_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-S010	100_2c_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-S011C1	200_2c_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-S012	200_1i_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-S002	200_1i_1gb	REV03	1GB	32MB	NA	NA	NA
TE0712-03-S013	200_2i_1gb	REV03	1GB	32MB	NA	NA	Without ETH PHY
TE0712-03-S016	200_2c_1gb	REV03	1GB	32MB	NA	NA	NA

Module Model	Board Part Short Name	PCB Revision Support	DDR	QSPI Flash	EMMC	Others	Notes
TE0712-03-S017	100_2c_1gb	REV03	1 GB	32MB	NA	NA	NA
TE0712-03-S018	200_2i_1gb	REV03	1 GB	32MB	NA	NA	NA

Table 4: Hardware Modules
*used as reference

Design supports following carriers:

Carrier Model	Notes
TE0701	
TE0703*	
TE0705	
TE0706	
TEBA0841	

Table 5: Hardware Carrier
*used as reference

Additional HW Requirements:

Additional Hardware	Notes
USB Cable for JTAG/UART	Check Carrier Board and Programmer for correct type
XMOD Programmer	Carrier Board dependent, only if carrier has no own FTDI

Table 6: Additional Hardware

4.5 Content

For general structure and usage of the reference design, see Project Delivery - AMD devices[2]

4.5.1 Design Sources

Type	Location	Notes
Vivado	\<project folder\>\block_design \<project folder\>\constraints \<project folder\>\ip_lib \<project folder\>\board_files	Vivado Project will be generated by TE Scripts
Vitis	\<project folder\>\sw_lib	Additional Software Template for Vitis and apps_list.csv with settings automatically for Vitis app generation
PetaLinux	\<project folder\>\os\petalinux	PetaLinux template with current configuration

Table 7: Design sources

4.5.2 Additional Sources

Type	Location	Notes
SI5338	\<project folder\>/misc/Si5338	SI5338 Project with current PLL Configuration

Table 8: Additional design sources

4.5.3 Prebuilt

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2 https://wiki.trenz-electronic.de/display/PD/Project+Delivery+-+AMD+devices

File	File-Extension	Description
BIT-File	*.bit	FPGA (PL Part) Configuration File
Boot Script	*.scr	Distro Boot file
DebugProbes-File	*.ltx	Definition File for Vivado/Vivado Labtools Debugging Interface
Diverse Reports	---	Report files in different formats
Hardware-Platform-Description-File	*.xsa	Exported Vivado hardware description file for Vitis and PetaLinux
LabTools Project-File	*.lpr	Vivado Labtools Project File
MCS-File	*.mcs	Flash Configuration File with Boot-Image (MicroBlaze or FPGA part only)
MMI-File	*.mmi	File with BRAM-Location to generate MCS or BIT-File with *.elf content (MicroBlaze only)
OS-Image	*.ub	Image with Linux Kernel (On Petalinux optional with Devicetree and RAM-Disk)
Software-Application-File	*.elf	Software Application for Zynq or MicroBlaze Processor Systems

Table 9: Prebuilt files (only on ZIP with prebuilt content)

4.5.4 Download

Reference Design is only usable with the specified Vivado/Vitis/PetaLinux version. Do never use different Versions of AMD(Xilinx) Software for the same Project.

Reference Design is available on:

- TE0712 "Test Board" Reference Design[3]

Microblaze Design with linux example.Basic description of TE Board Part Files is available on

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3 https://shop.trenz-electronic.de/Download/?path=Trenz_Electronic/Modules_and_Module_Carriers/4x5/TE0712/Reference_Design/2022.2/ test_board

5 Design Flow

> ⚠ Reference Design is available with and without prebuilt files. It's recommended to use TE prebuilt files for first launch.

See also: AMD Development Tools[4]

- AMD Development Tools[5]
- Vivado Projects - TE Reference Design[6]
- Project Delivery.[7]

The Trenz Electronic FPGA Reference Designs are TCL-script based project. Command files for execution will be generated with "_create_win_setup.cmd" on Windows OS and "_create_linux_setup.sh" on Linux OS.

TE Scripts are only needed to generate the vivado project, all other additional steps are optional and can also executed by Vivado/Vitis GUI. For currently Scripts limitations on Win and Linux OS see: Project Delivery Currently limitations of functionality[8]

> ⚠ **Caution!** Win OS has a 260 character limit for path lengths which can affect the Vivado tools. To avoid this issue, use Virtual Drive or the shortest possible names and directory locations for the reference design (for example "x:\<project folder>")

1. Run _create_win_setup.cmd/_create_linux_setup.sh and follow instructions on shell:

_create_win_setup.cmd/_create_linux_setup.sh

```
----------------------Set design paths------------------------
-- Run Design with: _create_win_setup
-- Use Design Path: <absolute project path>
--------------------------------------------------------------
-----------------------TE Reference Design--------------------
--------------------------------------------------------------
-- (0)  Module selection guide, project creation...prebuilt export...
-- (1)  Create minimum setup of CMD-Files and exit Batch
-- (2)  Create maximum setup of CMD-Files and exit Batch
-- (3)  (internal only) Dev
-- (4)  (internal only) Prod
-- (c)  Go to CMD-File Generation (Manual setup)
-- (d)  Go to Documentation (Web Documentation)
-- (g)  Install Board Files from Xilinx Board Store (beta)
-- (a)  Start design with unsupported Vivado Version (beta)
-- (x)  Exit Batch (nothing is done!)
----
Select (ex.:'0' for module selection guide):
```

2. Press 0 and enter to start "Module Selection Guide"
3. (optional Win OS) Generate Virtual Drive or use short directory for the reference design (for example x:\<design name>)

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4 https://wiki.trenz-electronic.de/display/PD/AMD+Development+Tools#AMDDevelopmentTools-XilinxSoftware-BasicUserGuides
5 https://wiki.trenz-electronic.de/display/PD/AMD+Development+Tools#AMDDevelopmentTools-XilinxSoftware-BasicUserGuides
6 https://wiki.trenz-electronic.de/display/PD/Vivado+Projects+-+TE+Reference+Design
7 https://wiki.trenz-electronic.de/display/PD/Project+Delivery+-+AMD+devices
8 https://wiki.trenz-electronic.de/display/PD/Project+Delivery+-+AMD+devices#ProjectDeliveryAMDdevices-Currentlylimitationsoffunctionality

4. Create project and follow instructions of the product selection guide, settings file will be configured automatically during this process.
   - optional for manual changes: Select correct device and AMD(Xilinx) install path on "design_basic_settings.cmd" and create Vivado project with "vivado_create_project_guimode.cmd"

   > ⚠ Note: Select correct one, see also Vivado Board Part Flow[9]

5. Create hardware description file (.xsa file) for PetaLinux project and export to prebuilt folder

   run on Vivado TCL (Script generates design and export files into "\prebuilt\hardware\")

   ```
   \prebuilt\hardware\")">
   TE::hw_build_design -export_prebuilt
   ```

   > ⓘ Using Vivado GUI is the same, except file export to prebuilt folder.

6. Create and configure your PetaLinux project with exported .xsa-file, see PetaLinux KICKstart[10]
   - use TE Template from "<project folder>\os\petalinux"
   - use exported .xsa file from "<project folder>\prebuilt\hardware\<short name>" . **Note:** HW Export from Vivado GUI creates another path as default workspace.
   - The petalinux build images are located in the "<plnx-proj-root>/images/linux" directory

   > ⓘ **Important Note**: Select correct Flash partition offset on petalinux-config: Subsystem Auto HW Settings → Flash Settings, FPGA+Boot+bootenv=0xA00000 (increase automatically generate Boot partition), increase image size to A:, see Config (see page 31)

7. Configure the **boot.scr** file as needed, see Distro Boot with Boot.scr[11]. Kernel flash address and kernel size are set here.

8. Copy PetaLinux build image files to prebuilt folder
   - copy **u-boot.elf**, **image.ub** and **boot.scr** from "<plnx-proj-root>/images/linux" to prebuilt folder

   > ⓘ "<project   folder>\prebuilt\os\petalinux\<ddr   size>"   or   "<project folder>\prebuilt\os\petalinux\<short name>"

9. Generate Programming Files with Vitis

   run on Vivado TCL (Script generates applications and bootable files, which are defined in "test_board\sw_lib\apps_list.csv")

   ```
   TE::sw_run_vitis -all
   TE::sw_run_vitis (optional; Start Vitis from Vivado GUI or start with TE
   Scripts on Vivado TCL)
   ```

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9 https://wiki.trenz-electronic.de/display/PD/Vivado+Board+Part+Flow
10 https://wiki.trenz-electronic.de/display/PD/PetaLinux+KICKstart
11 https://wiki.trenz-electronic.de/display/PD/Distro+Boot+with+Boot.scr

> ⚠ TCL scripts generate also platform project, this must be done manually in case GUI is used. See
> Vitis[12]

10. (Optional) BlockRam Firmware Update
    a. Copy "<project folder>\prebuilt\software\<short name>\spi_bootloader.elf" into "<project folder>\firmware\microblaze_0\"
    b. Copy "<project folder>\workspace\sdk\scu_te0712\Release\scu_te0712.elf" into "\firmware\microblaze_mcs_0\"
    c. Regenerate Vivado Project or Update Bitfile only with "spi_bootloader.elf" and "scu_te0712.elf"

```
TE::hw_build_design -export_prebuilt
TE::sw_run_vitis -all
```

Trenz Electronic provides a tcl based built environment based on AMD(Xilinx) Design Flow.

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[12] https://wiki.trenz-electronic.de/display/PD/Vitis

6 Launch

6.1 Programming

> ⚠ Check Module and Carrier TRMs for proper HW configuration before you try any design.
> Reference Design is also available with prebuilt files. It's recommended to use TE prebuilt files for first launch.

AMD(Xilinx) documentation for programming and debugging: Vivado/Vitis/SDSoC-Xilinx Software Programming and Debugging[13]

6.1.1 Get prebuilt boot binaries

1. Run _create_win_setup.cmd/_create_linux_setup.sh and follow instructions on shell
2. Press 0 and enter to start "Module Selection Guide"
    a. Select assembly version
    b. Validate selection
    c. Select create and open delivery binary folder

    > ⓘ Note: Folder "<project folder>_binaries_<Article Name>" with subfolder "boot_<app name>" for different applications will be generated

6.1.2 QSPI-Boot mode

Option for **u-boot.mcs** on QSPI Flash.
(u-boot.mcs contains all files necessary to boot up linux)

1. Connect the **USB cable**(JTAG) and **power supply** on carrier with module
2. Open Vivado Project with "vivado_open_existing_project_guimode.cmd" or if not created, create with "vivado_create_project_guimode.cmd".
    Enter the following TCL-Command into the TCL-Console inside Vivado to program the QSPI Flash.

    run on Vivado TCL (Script programs u-boot.mcs onto QSPI flash)

    ```
    TE::pr_program_flash -swapp u-boot
    ```

3. Reboot (if not done automatically)

6.1.3 SD-Boot mode

Not used on this Example.

6.1.4 JTAG

Not used on this Example.

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[13] https://wiki.trenz-electronic.de/display/PD/AMD+Development+Tools#AMDDevelopmentTools-XilinxSoftwareProgrammingandDebugging

6.2 Usage

1. Prepare HW like described on section Programming (see page 24)
2. Connect UART USB (most cases same as JTAG)
3. Select QSPI as Boot Mode

> ⓘ Note: See TRM of the Carrier, which is used.

4. Power On PCB and push the reset button if present on carrier.
   boot process

   1. FPGA Loads Bitfile from Flash,

   2. MCS Firmware configure SI5338 (per default off with REV03) and starts Microblaze,

   3. SPI Bootloader from Bitfile Firmware loads U-Boot into DDR (This takes a while),

   4. U-boot loads Linux from QSPI Flash into DDR

6.2.1 Linux

1. Open Serial Console (e.g. putty)
   - Speed: 9600
   - COM Port

   > ⓘ Win OS, see device manager, Linux OS see dmesg |grep tty (UART is *USB1)

2. Boot process takes a while, please wait...

```
*******************************************************************

CPLD_REVISION = 3

*******************************************************************


-----------------------------------------------------------------

Transferring execution to program @ 0x80100000


U-Boot 2022.01-00194-gb31476685d-dirty (Sep 20 2022 - 06:35:33 +0000)

Model: Xilinx MicroBlaze
DRAM:  1 GiB
Loading Environment from nowhere... OK
In:    serial
Out:   serial
Err:   serial
Model: Xilinx MicroBlaze
Net:   EMACLITE: 40e00000, phyaddr 1, 1/1
eth0: ethernet@40e00000
U-BOOT for microblaze-generic
```

3. Linux Console:

```
petalinux login: petalinux
     -> assign new password
```

> (i) Note: Wait until Linux boot finished.
> Linux boot process is slower on Microblaze.

4. You can use Linux shell now.

```
udhcpc              (ETH0 check)
```

6.2.2 Vivado HW Manager

- Open Vivado HW-Manager and add VIO signal to dashboard (*.ltx located on prebuilt folder).
    - Set radix from VIO signals (MGT REF, MIG_OUT, CLK1B, CLK0) to **unsigned integer**.
      Note: Frequency Counter is inaccurate and displayed unit is Hz
- Monitoring:
    - MGT REF~125MHz, MIG_50MHZ~50MHz., CLK1B ~50MHz, CLK0~100MHz
    - System reset from MCS and GIO outputs
    - **1.** → Si5338 PLL was programmed 0 = NO | 1 = YES
    - **2.** → Error occurred during PLL programming 0 = NO | 1 = YES
    - **3.** → Module Revision (Can be set in the Blockdiagram → SC0712 IP)
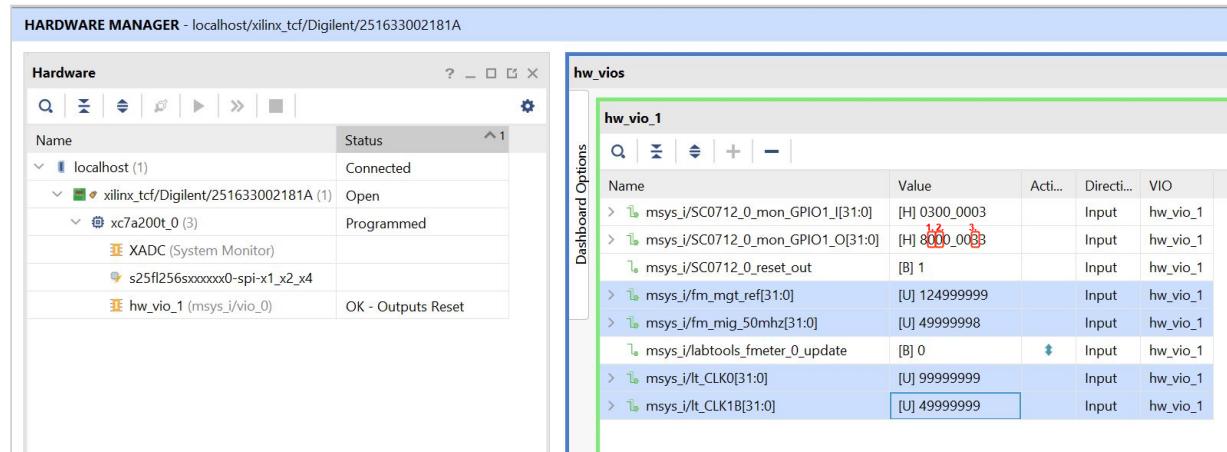
7 System Design - Vivado

7.1 Block Design
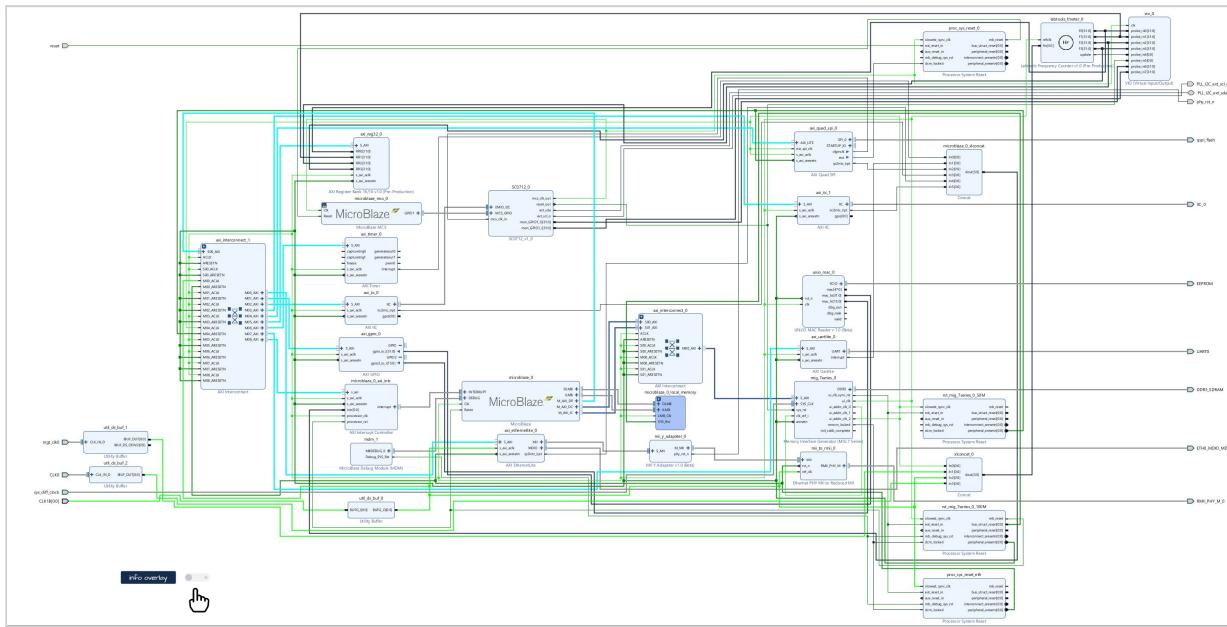
7.2 Constraints

7.2.1 Basic module constraints

_i_bitgen_common.xdc

```
set_property BITSTREAM.GENERAL.COMPRESS TRUE [current_design]
set_property BITSTREAM.CONFIG.CONFIGRATE 66 [current_design]
set_property CONFIG_VOLTAGE 3.3 [current_design]
set_property CFGBVS VCCO [current_design]
set_property CONFIG_MODE SPIx4 [current_design]
set_property BITSTREAM.CONFIG.SPI_32BIT_ADDR YES [current_design]
set_property BITSTREAM.CONFIG.SPI_BUSWIDTH 4 [current_design]
set_property BITSTREAM.CONFIG.M1PIN PULLNONE [current_design]
set_property BITSTREAM.CONFIG.M2PIN PULLNONE [current_design]
set_property BITSTREAM.CONFIG.M0PIN PULLNONE [current_design]

set_property BITSTREAM.CONFIG.USR_ACCESS TIMESTAMP [current_design]
```

_i_bitgen.xdc

```
set_property BITSTREAM.CONFIG.UNUSEDPIN PULLDOWN [current_design]
```

7.2.2 Design specific constraints

_i_reset.xdc

```
set_property PULLDOWN true [get_ports reset]
```

_i_io.xdc

```
#I2C
#set_property PACKAGE_PIN W21 [get_ports PLL_I2C_scl_io]
#set_property IOSTANDARD LVCMOS33 [get_ports PLL_I2C_scl_io]
#set_property PACKAGE_PIN T20 [get_ports PLL_I2C_sda_io]
#set_property IOSTANDARD LVCMOS33 [get_ports PLL_I2C_sda_io]
set_property PACKAGE_PIN W21 [get_ports PLL_I2C_ext_scl_o]
set_property IOSTANDARD LVCMOS33 [get_ports PLL_I2C_ext_scl_o]
set_property PACKAGE_PIN T20 [get_ports PLL_I2C_ext_sda]
set_property IOSTANDARD LVCMOS33 [get_ports PLL_I2C_ext_sda]

#Reset
set_property PACKAGE_PIN T3 [get_ports reset]
set_property IOSTANDARD LVCMOS15 [get_ports reset]
#CLKS
set_property PACKAGE_PIN R4 [get_ports {CLK1B[0]}]
set_property IOSTANDARD LVCMOS15 [get_ports {CLK1B[0]}]
set_property PACKAGE_PIN K4 [get_ports {CLK0_clk_p[0]}]
set_property IOSTANDARD DIFF_SSTL15 [get_ports {CLK0_clk_p[0]}]

#ETH PHY
set_property PACKAGE_PIN N17 [get_ports phy_rst_n]
set_property IOSTANDARD LVCMOS33 [get_ports phy_rst_n]

#EEPROM onewire (MAC ADDRESS)
set_property IOSTANDARD LVCMOS33 [get_ports EEPROM_tri_io]
set_property PACKAGE_PIN V22 [get_ports EEPROM_tri_io]

#I2C connected to CPLD
set_property -dict {IOSTANDARD LVCMOS33 PACKAGE_PIN W22} [get_ports IIC_0_scl_io]
set_property -dict {IOSTANDARD LVCMOS33 PACKAGE_PIN U22} [get_ports IIC_0_sda_io]
```

_i_timing.xdc

```
create_clock -period 8.000 -name mgt_clk0_clk_p -waveform {0.000 4.000}
[get_ports mgt_clk0_clk_p]


create_clock -period 10.000 -name {CLK0_clk_p[0]} -waveform {0.000 5.000}
[get_ports {CLK0_clk_p[0]}]
create_clock -period 20.000 -name {CLK1B[0]} -waveform {0.000 10.000} [get_ports
{CLK1B[0]}]
create_clock -period 15.152 -name CFGMCLK -waveform {0.000 7.576} [get_pins
-hierarchical -filter {NAME =~*NO_DUAL_QUAD_MODE.QSPI_NORMAL/*STARTUP_7SERIES_GEN.
STARTUP2_7SERIES_inst/CFGMCLK}]


set_false_path -from [get_clocks {CLK0_clk_p[0]}] -to [get_clocks clk_pll_i]
set_false_path -from [get_clocks mgt_clk0_clk_p] -to [get_clocks clk_pll_i]
set_false_path -from [get_pins {msys_i/SC0712_0/U0/rst_delay_i_reg[3]/C}] -to
[get_pins -hierarchical -filter {NAME =~*u_msys_mig_7series_0_0_mig/
u_ddr3_infrastructure/rstdiv0*/PRE}]
set_false_path -from [get_clocks -of_objects [get_pins msys_i/mig_7series_0/
u_msys_mig_7series_0_0_mig/u_ddr3_infrastructure/gen_ui_extra_clocks.mmcm_i/
CLKFBOUT]] -to [get_clocks mgt_clk0_clk_p]
set _xlnx_shared_i0 [get_pins {msys_i/vio_0/inst/PROBE_IN_INST/
probe_in_reg_reg[*]/D}]
set_false_path -from [get_pins {msys_i/labtools_fmeter_0/U0/F_reg[*]/C}] -to
$_xlnx_shared_i0
set_false_path -from [get_pins msys_i/labtools_fmeter_0/U0/COUNTER_REFCLK_inst/
bl.DSP48E_2/CLK] -to $_xlnx_shared_i0
set_false_path -from [get_pins {msys_i/labtools_fmeter_0/U0/
FMETER_gen[*].COUNTER_F_inst/bl.DSP48E_2/CLK}] -to [get_pins {msys_i/
labtools_fmeter_0/U0/F_reg[*]/D}]
```

8 Software Design - Vitis

For Vitis project creation, follow instructions from:

Vitis[14]

8.1 Application

Template location: "<project folder>\sw_lib\sw_apps\"

8.1.1 scu_te0712

MCS Firmware to configure SI5338 and Reset System.

8.1.2 spi_bootloader

TE modified SPI Bootloader from Henrik Brix Andersen[15].

Bootloader to load app or second bootloader from flash into DDR.

Here it loads the u-boot.elf from QSPI-Flash to RAM. Hence u-boot.srec becomes redundant.

Descriptions:

- Modified Files: bootloader.c
- Changes:
    - Change the SPI defines in the header
    - Add some reiteration in the frist spi read call

8.1.3 hello_te0712

Hello TE0712 is a AMD(Xilinx) Hello World example as endless loop instead of one console output.

8.1.4 u-boot

U-Boot.elf is generated with PetaLinux. Vitis is used to generate u-boot.srec(obsolete). Vivado to generate *.mcs

---

14 https://wiki.trenz-electronic.de/display/PD/Vitis
15 https://github.com/henrikbrixandersen/elf-bootloader

9 Software Design - PetaLinux

For PetaLinux installation and project creation, follow instructions from:

- PetaLinux KICKstart[16]

9.1 Config

Start with **petalinux-config** or **petalinux-config --get-hw-description**

(Tipp: Search for Settings with shortcut "Shift"+"/")

Changes:

- SUBSYSTEM_FLASH_AXI_QUAD_SPI_0_BANKLESS_PART0_SIZE = **0x5E0000** (fpga)
- SUBSYSTEM_FLASH_AXI_QUAD_SPI_0_BANKLESS_PART1_SIZE = **0x400000** (boot)
- SUBSYSTEM_FLASH_AXI_QUAD_SPI_0_BANKLESS_PART2_SIZE = **0x20000** (bootenv)
- SUBSYSTEM_FLASH_AXI_QUAD_SPI_0_BANKLESS_PART3_SIZE = **0xB00000** (kernel)
    - (with this kernel flash address is 0xA00000 (fpga+boot+bootenv) and Kernel size 0xB00000)

9.2 U-Boot

Start with **petalinux-config -c u-boot**

Changes:

- CONFIG_ENV_IS_NOWHERE=y
- # CONFIG_ENV_IS_IN_SPI_FLASH is not set
- # CONFIG_PHY_ATHEROS is not set
- # CONFIG_PHY_BROADCOM is not set
- # CONFIG_PHY_DAVICOM is not set
- # CONFIG_PHY_LXT is not set
- # CONFIG_PHY_MICREL_KSZ90X1 is not set
- # CONFIG_PHY_MICREL is not set
- # CONFIG_PHY_NATSEMI is not set
- # CONFIG_PHY_REALTEK is not set
- CONFIG_RGMII=y

Content of **platform-top.h** located in <plnx-proj-root>\project-spec\meta-user\recipes-bsp\u-boot\files:

```
#include <configs/microblaze-generic.h>
#include <configs/platform-auto.h>

#define CONFIG_SYS_BOOTM_LEN 0xF000000
```

9.3 Device Tree

Content of **system-user.dtsi** located in <petalinux project directory>\project-spec\meta-user\recipes-bsp\device-tree\files:

---

[16] https://wiki.trenz-electronic.de/display/PD/PetaLinux+KICKstart

```
/include/ "system-conf.dtsi"
/ {
};

/* QSPI PHY */

&axi_quad_spi_0 {
    #address-cells = <1>;
    #size-cells = <0>;
    flash0: flash@0 {
        compatible = "jedec,spi-nor";
        spi-tx-bus-width=<1>;
        spi-rx-bus-width=<4>;
        reg = <0x0>;
        #address-cells = <1>;
        #size-cells = <1>;
        spi-max-frequency = <25000000>;
    };
};


/* ETH PHY */
&axi_ethernetlite_0 {
    phy-handle = <&phy0>;
    mdio {
        #address-cells = <1>;
        #size-cells = <0>;
        phy0: phy@0 {
            device_type = "ethernet-phy";
            reg = <1>;
        };
    };
};
```

9.4 Kernel

Start with **petalinux-config -c kernel**

Changes:

- No changes.

9.5 Rootfs

Start with **petalinux-config -c rootfs**

Changes:

- # CONFIG_dropbear is not set
- # CONFIG_dropbear-dev is not set
- # CONFIG_dropbear-dbg is not set
- # CONFIG_package-group-core-ssh-dropbear is not set
- # CONFIG_packagegroup-core-ssh-dropbear-dev is not set

- # CONFIG_packagegroup-core-ssh-dropbear-dbg is not set
- # CONFIG_imagefeature-ssh-server-dropbear is not set

optional: to change the password settings at startup look at Adding extra users to the petalinux system[17].

"Dropbear" is part of the "petalinux-image-minimal" configuration, so changes in the petalinux rootfs will not be applied. To remove "dropbear" anyway, enter the following line in *petalinuxbsp.conf* in ..\petalinux\project-spec\meta-user\conf:

```
PACKAGE_EXCLUDE += " dropbear dropbear-openssh-sftp-server dropbear-dev dropbear-
dbg dropbear-openssh-sftp-server packagegroup-core-ssh-dropbear packagegroup-
core-ssh-dropbear-dbg packagegroup-core-ssh-dropbear-dev"
```

9.6 Applications

No additional application.

---

17 https://docs.xilinx.com/r/2021.1-English/ug1144-petalinux-tools-reference-guide/Adding-Extra-Users-to-the-PetaLinux-System

10 Additional Software

10.1 SI5338

File location "<project folder>\misc\Si5338\Si5338-*.slabtimeproj"

General documentation how you work with this project will be available on Si5338[18]

---

[18] https://wiki.trenz-electronic.de/display/PD/Si5338

11 Appx. A: Change History and Legal Notices

11.1 Document Change History

To get content of older revision got to "Change History" of this page and select older document revision number.

Date	Document Revision	Authors	Description
📅 2023-05-1 0	v.48 (see page 6)	Waldemar Hanemann[19]	• 2022.2 update • added Si5338 initialisation option in SC0712
2022-08-15	v.43	Waldemar Hanemann	• reduced bitdelay in PLL I2C programming for faster startup • update TE Board Part List • corrected spelling mistake in apps_list.csv (msc → mcs)
2022-08-15	v.42	Waldemar Hanemann	• scu_te0712.elf built problem → see known issues
2022-02-16	v.41	Waldemar Hanemann	• new spi bootloader by Henrik Brix Andersen • adjusted offsets
2022-01-18	v.40	Waldemar Hanemann	• MB_MCS elf-File bugfix • eeprom Skript bugfix
2022-01-11	v.39	Waldemar Hanemann	• 2021.2 update • added eeprom interface to get MAC address • added boot script

---

19 https://wiki.trenz-electronic.de/display/~w.hanemann

Date	Document Revision	Authors	Description
2021-06-28	v.38	@Manuela Strücker	• 2020.2 update • document style update • update TE Board Part List
2021-06-28	v.37	John Hartfiel	• typo correction
2020-03-25	v.35	John Hartfiel	• update scripts
2020-01-21	v.34	John Hartfiel	• update scripts, new features and linux support
2020-01-08	v.33	John Hartfiel	• 2019.2 release
2019-04-18	v.32	John Hartfiel	• small design changes
2019-02-22	v.31	John Hartfiel	• 2018.3 release (include design reworks)
2018-09-06	v.30	John Hartfiel	• 2018.2 release
2018-05-25	v.28	John Hartfiel	• Design update
2018-05-08	v.27	John Hartfiel	• Know Issues • Documentation
2018-04-12	v.23	John Hartfiel	• Design Update
2018-03-28	v.22	John Hartfiel	• Know Issue for PCB REV01 only • Fix typo • New assembly variant
2018-02-13	v.19	John Hartfiel	• Release 2017.4
2018-01-08	v.16	John Hartfiel	• Add SCU source path
2017-12-15	v.15	John Hartfiel	• Update Design and Description

Date	Document Revision	Authors	Description
2017-11-07	v.11	John Hartfiel	• Update Design Files
2017-10-06	v.10	John Hartfiel	• small Document Update
2017-10-05	v.8	John Hartfiel	• Release 2017.2
2017-09-11	v.1	@ John Hartfiel[20]	• Initial release
---	All	@ John Hartfiel[21] , Manuela Strücker[22] , Waldemar Hanemann[23]	---

Table 10: Document change history.

11.2 Legal Notices

11.3 Data Privacy

Please also note our data protection declaration at https://www.trenz-electronic.de/en/Data-protection-Privacy

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20 https://wiki.trenz-electronic.de/display/~j.hartfiel
21 https://wiki.trenz-electronic.de/display/~j.hartfiel
22 https://wiki.trenz-electronic.de/display/~m.struecker
23 https://wiki.trenz-electronic.de/display/~w.hanemann

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WEEE

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24 http://guidance.echa.europa.eu/
25 https://echa.europa.eu/candidate-list-table
26 http://www.echa.europa.eu/

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🗓 2019-06-07